

## CLAIMS

1. A polishing pad having a polishing surface that is configured to polish a surface of a substrate, comprising:

a plurality of first polishing elements that each comprise a plurality of first polymer layers that comprise a first polymer material, wherein at least one of the plurality of first polymer layers forms the polishing surface; and

a base region that is disposed between at least one of the plurality of first polishing elements and a supporting surface of the polishing pad, wherein the base region comprises a plurality of layers that each comprise a plurality of cured droplets of a first resin precursor composition material and a plurality of cured droplets of a second resin precursor composition material,

wherein the polishing surface of each of the plurality of first polishing elements have a formed shape, and the formed shape comprises a toroid, an arc, at least a portion of a spiral, a circle, an oval, a square, a rectangle, a triangle, or a polygon, or a combination thereof, and wherein the first polymer material has a storage modulus that is greater than the material within the plurality of layers used to form the base region.